ABSTRACT

MULTI-CHIP MODULE

On the surface of a first microchip (3) at least one electrically conductive track (15) is mounted. An electrical conduct (9) which is connected to the conductive track (15) is provided for electrical connection of the conductive track (15) to the outside of a multi-chip module. The track (15) facilitates the handling of electrical interconnections (19) to be made between the microchips (3,5) and the conducts (9).

Fig. 3